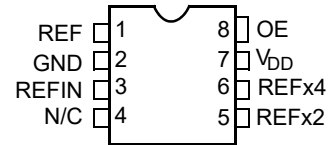


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Pin Configurations

Figure 1. 8-pin SOIC pinout



Pin Description

Pin	Signal ^[1]	Description
1	REF	REF output (1× reference input)
2	GND	Ground
3	REFIN	Input reference frequency, 5 V tolerant input
4	N/C	No connect
5	REF×2	2× reference input
6	REF×4	4× reference input
7	V _{DD}	3.3 V supply
8	OE	Output enable (weak pull-up)

Note

1. Weak pull-down on all outputs.

Maximum Ratings

Supply voltage to ground potential -0.5 V to +7.0 V
 DC input voltage (except ref) -0.5 V to $V_{DD} + 0.5$ V
 DC input voltage REFIN -0.5 V to 7 V

Storage temperature -65 °C to +150 °C
 Junction temperature 150 °C
 Static discharge voltage
 (per MIL-STD-883, method 3015) > 2000 V

Operating Conditions

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T_A	Operating temperature (ambient temperature)	0	70	°C
C_L	Load capacitance, 10 MHz < F_{OUT} < 133.33 MHz	–	18	pF
	Load capacitance, 133.33 MHz < F_{OUT} < 166.67 MHz	–	12	pF
C_{IN}	Input capacitance	–	7	pF
t_{PU}	Power-up time for all V_{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW voltage		–	0.8	V
V_{IH}	Input HIGH voltage		2.0	–	V
I_{IL}	Input LOW current	$V_{IN} = 0$ V	–	100	μA
I_{IH}	Input HIGH current	$V_{IN} = V_{DD}$	–	50	μA
V_{OL}	Output LOW voltage [2]	$I_{OL} = 8$ mA	–	0.4	V
V_{OH}	Output HIGH voltage [2]	$I_{OH} = -8$ mA	2.4	–	V
I_{DD}	Supply current	Unloaded outputs, REFIN = 41.67 MHz	–	45	mA
		Unloaded outputs, REFIN = 25 MHz	–	32	mA
		Unloaded outputs, REFIN = 10 MHz	–	18	mA

Thermal Resistance

Parameter [3]	Description	Test Conditions	8-pin SOIC	Unit
θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51.	140	°C/W
θ_{JC}	Thermal resistance (junction to case)		54	°C/W

Notes

- Parameter is guaranteed by design and characterization. It is not 100% tested in production.
- These parameters are guaranteed by design and are not tested.

Switching Characteristics

Parameter	Name	Test Conditions	Min	Typ	Max	Unit
1/t ₁	Output frequency	18-pF load	10	–	133.33	MHz
		12-pF load	–	–	166.67	MHz
	Duty cycle ^[4] = t ₂ ÷ t ₁	Measured at V _{DD} /2	40	50	60	%
t ₃	Rise time ^[4]	Measured between 0.8 V and 2.0 V	–	–	1.20	ns
t ₄	Fall time ^[4]	Measured between 0.8 V and 2.0 V	–	–	1.20	ns
t ₅	Output to output skew on rising edges ^[4]	All outputs equally loaded Measured at V _{DD} /2	–	–	200	ps
t ₆	Delay, REFIN rising edge to REF rising edge ^[4]	Measured at V _{DD} /2 from REFIN to any output	–	–	±200	ps
t ₇	Device to device skew ^[4]	Measured at V _{DD} /2 on the REF pin of the device (pin 1)	–	–	400	ps
t _J	Period jitter ^[4]	Measured at F _{OUT} < 133.33 MHz, loaded outputs, 18-pF load	–	±80	±175	ps
t _{LOCK}	PLL lock time ^[4]	Stable power supply, valid clocks presented on REFIN	–	–	1.0	ms

Note

4. All parameters are specified with loaded outputs.

Switching Waveforms

Figure 2. Duty Cycle Timing

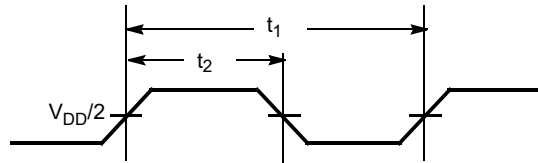


Figure 3. All Outputs Rise/Fall Time

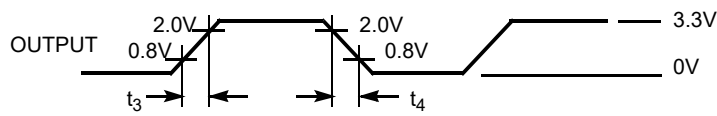


Figure 4. Output to Output Skew

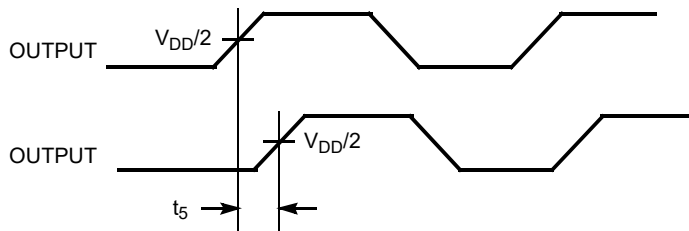


Figure 5. Input to Output Propagation Delay

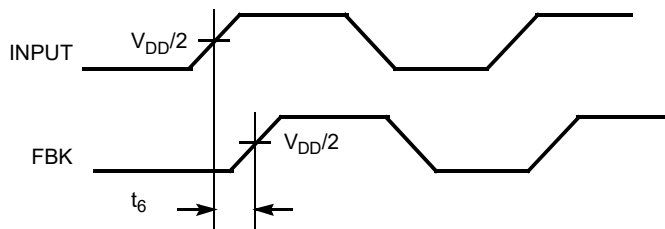
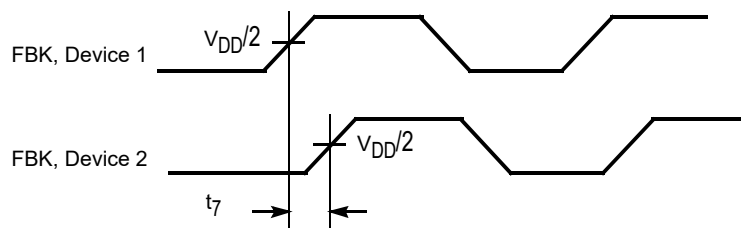
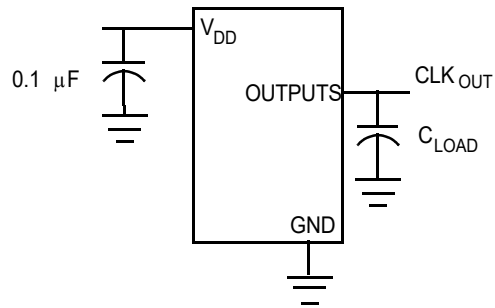


Figure 6. Device to Device Skew



Test Circuits

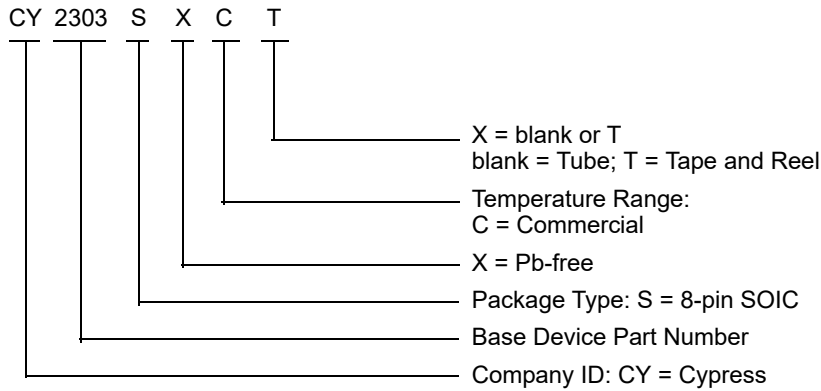
Figure 7. Test Circuit #1



Ordering Information

Ordering Code	Package Type	Operating Range
Pb-free		
CY2303SXC	8-pin SOIC (150 Mils)	Commercial (0 °C to 70 °C)
CY2303SXCT	8-pin SOIC (150 Mils) - Tape and Reel	Commercial (0 °C to 70 °C)

Ordering Code Definitions

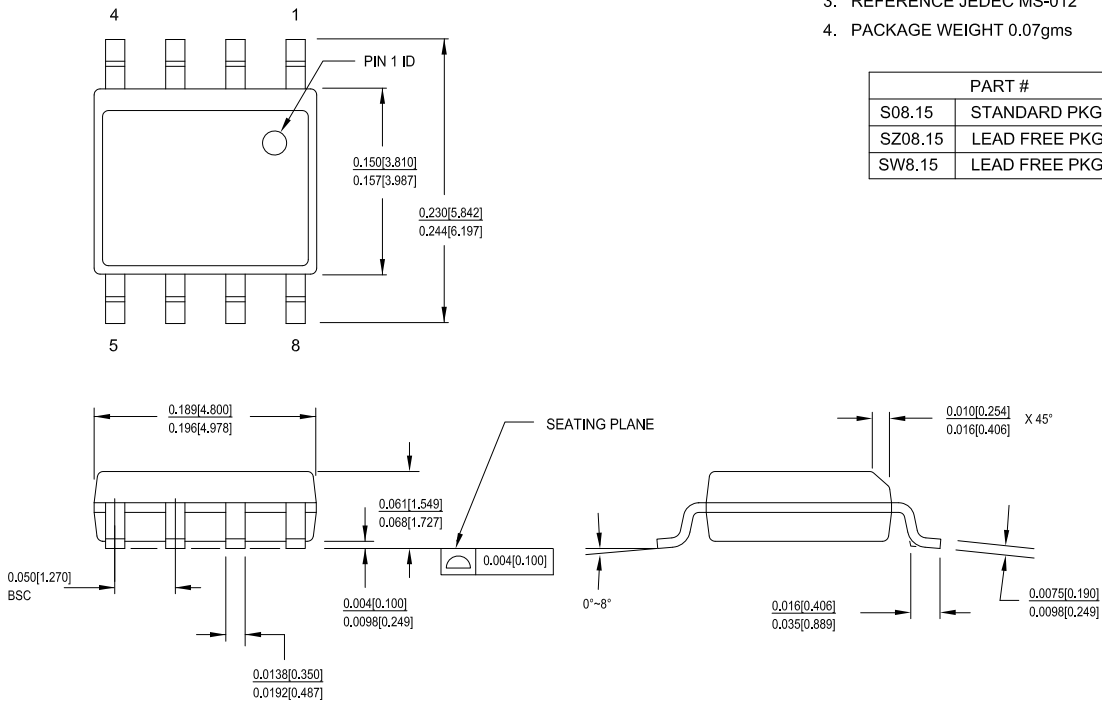


Package Diagram

Figure 8. 8-pin SOIC (150 Mils) S0815/SZ815/SW815 Package Outline, 51-85066

1. DIMENSIONS IN INCHES[MM] MIN. MAX.
2. PIN 1 ID IS OPTIONAL, ROUND ON SINGLE LEADFRAME RECTANGULAR ON MATRIX LEADFRAME
3. REFERENCE JEDEC MS-012
4. PACKAGE WEIGHT 0.07gms

PART #	
S08.15	STANDARD PKG
SZ08.15	LEAD FREE PKG
SW8.15	LEAD FREE PKG



51-85066 *I

Acronyms

Acronym	Description
FBK	Feedback
OE	Output Enable
PLL	Phase Locked Loop
REFIN	Reference Input

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
Hz	hertz
kHz	kilohertz
MHz	megahertz
μA	microampere
μF	microfarad
μs	microsecond
μV	microvolt
mA	milliampere
mm	millimeter
ms	millisecond
mV	millivolt
ns	nanosecond
pA	picoampere
pF	picofarad
ps	picosecond
V	volt

Reference Documents

Reference documents are available through your local Cypress sales representative. You can also direct your requests to tsbusdev@cypress.com.

Document Number	Document Title	Description
NA	NA	NA

Errata

This section describes the errors, workaround solution and silicon design fixes for Cypress zero delay clock buffers belonging to the families CY2303. Details include errata trigger conditions, scope of impact, available workarounds, and silicon revision applicability. Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Table 1. Part Numbers Affected

Part Number	Device Variants
CY2303SXC	All Variants
CY2303SXCT	All Variants

CY2303 Errata Summary

Items	Part Number	Fix Status
Start up lock time issue [CY2303]	All	Silicon fixed. New silicon available from WW 10 of 2013

CY2303 Qualification Status of fixed silicon

Product Status: In production

Qualification report last updated on 11/27/2012

<http://www.cypress.com/?rID=72595>

1. Start up lock time issue

■ Problem Definition

Output of CY2304 fails to locks within 1 ms upon power up (as per datasheet spec)

■ Parameters Affected

PLL lock time

■ Trigger Condition(s)

Start up

■ Scope of Impact

It can impact the performance of system and its throughput

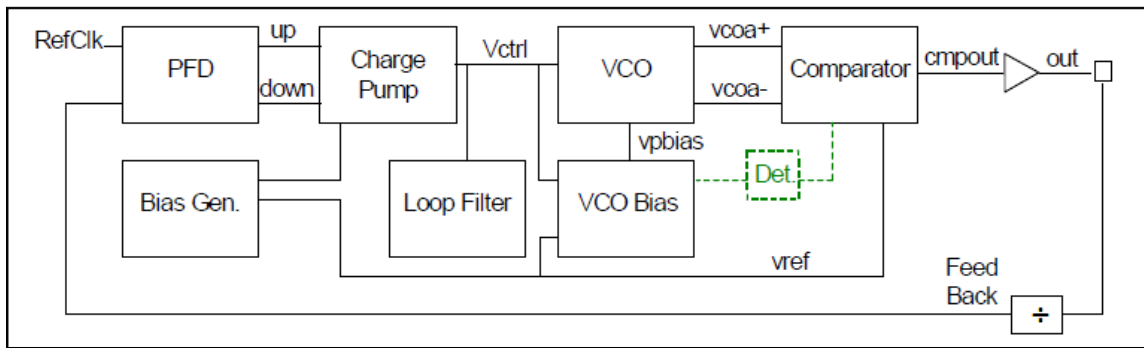
■ Workaround

Apply reference input (RefClk) before power up (V_{DD}). If RefClk is applied after power up, noise gets coupled on the output and propagates back to the PLL causing it to take higher time to acquire lock. If reference input is present during power up, noise will not propagate to the PLL and device will start up normally without problems.

■ Fix Status

This issue is due to design marginality. Two minor design modifications have been made to address this problem.

- Addition of VCO bias detector block as shown in the following figure keeps comparator power down till VCO bias is present and thereby eliminating the propagation of noise to feedback.
- Bias generator enhancement for successful initialization.



Document History Page

Document Title: CY2303, Phase-Aligned Clock Multiplier				
Document Number: 38-07249				
Rev.	ECN	Orig. of Change	Submission Date	Description of Change
**	110514	SZV	01/07/2002	Changed from spec number: 38-01036 to 38-07249.
*A	121852	RBI	12/14/2002	Updated Operating Conditions : Added t _{PU} parameter and its details.
*B	390413	RGL	08/10/2005	Updated Switching Characteristics : Added typical value for t _J parameter. Updated Ordering Information : Updated part numbers.
*C	2568533	AESA	09/23/2008	Updated Selector Guide: Removed CY2303SC and CY2303SI part number related information. Updated Ordering Information : Updated part numbers. Updated to new template.
*D	2897294	KVM	03/22/2010	Removed Industrial Temperature Range related information in all instances across the document. Removed Selector Guide. Updated Ordering Information : Updated part numbers. Updated Package Diagram : spec 51-85066 – Changed revision from *C to *D. Updated to new template.
*E	3026183	BASH	09/01/2010	Updated Switching Characteristics : Changed typical value of t _J parameter from 80 ps to ±80 ps. Updated Ordering Information : No change in part numbers. Added Ordering Code Definitions . Added Acronyms , and Units of Measure . Added Reference Documents . Completing Sunset Review.
*F	4018186	CINM	06/10/2013	Updated Package Diagram : spec 51-85066 – Changed revision from *D to *F. Added Errata .
*G	4127379	CINM	10/23/2013	Updated to new template. Completing Sunset Review.
*H	4578443	TAVA	10/25/2014	Updated Functional Description : Added “For a complete list of related documentation, click here .” at the end.
*I	5270465	PSR	05/13/2016	Added Thermal Resistance . Updated Package Diagram : spec 51-85066 – Changed revision from *F to *H. Updated to new template.
*J	5515677	TAVA	11/09/2016	Updated to new template. Completing Sunset Review.
*K	6043496	PAWK	01/24/2018	Updated Package Diagram : spec 51-85066 – Changed revision from *H to *I. Updated to new template.

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